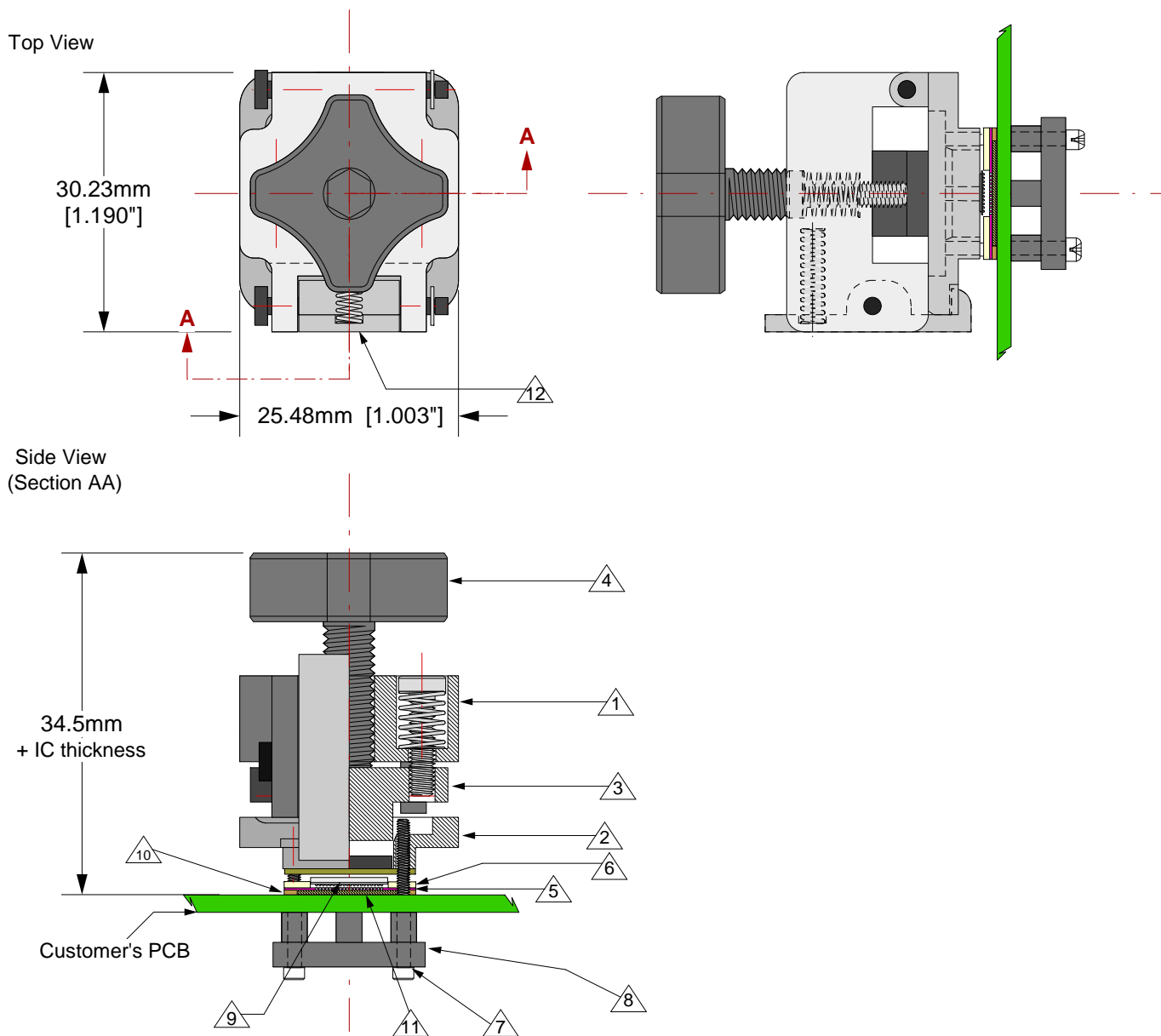


Clamshell BGA Elastomer Socket




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

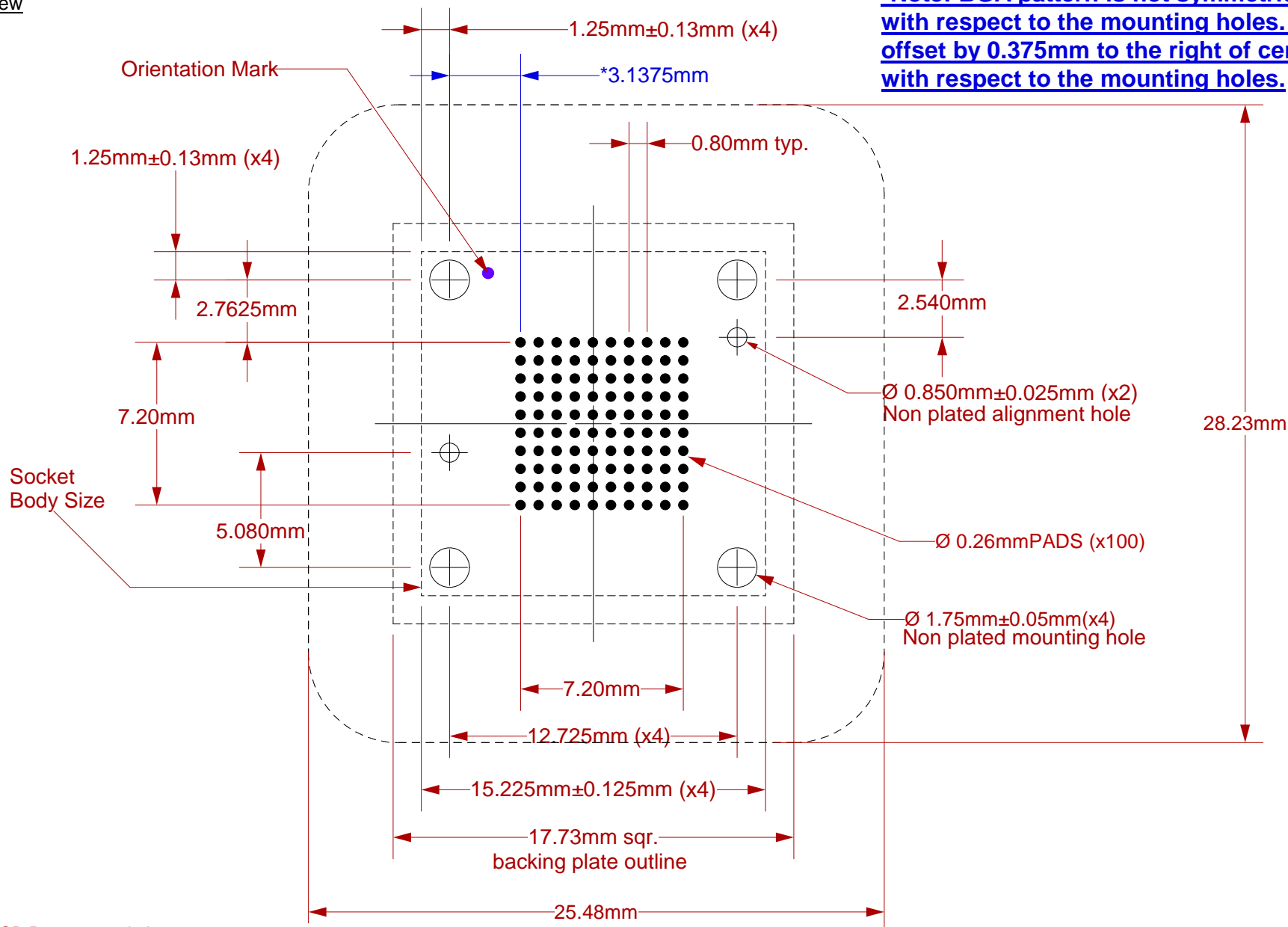
Materials:

- △1 Clam Shell Lid: Black anodized Aluminum. Height = 16.5 mm.
- △2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- △3 Compression Plate: Black anodized Aluminum. Thickness = 8.5 mm.
- △4 Compression Screw: Clear anodized Aluminum. Height = 25 mm, Fluted Knob
- △5 Ball Guide: Kapton polyimide.
- △6 IC Guide: Torlon
- △7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- △8 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm
- △9 Customer's BGA IC
- △10 Elastomer Guide: Non-clad FR4. Thickness = 0.735mm.
- △11 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △12 Latch: Black anodised Aluminum.

| | | | | |
|---|--|---------------------------|-------------------|----------------|
|  | CG-BGA-4011 Drawing | Status: Released | Scale: - | Rev: B |
| | © 2011 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com | Drawing: E. Smolentseva | | Date: 10/26/11 |
| | | File: CG-BGA-4011 Dwg.mcd | Modified: 3/31/14 | |

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes. It is offset by 0.375mm to the right of center with respect to the mounting holes.**




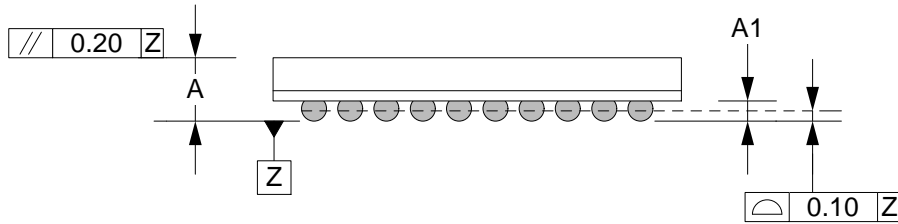
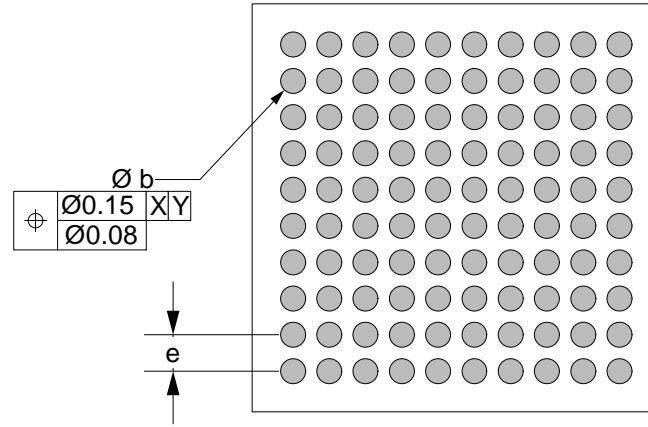
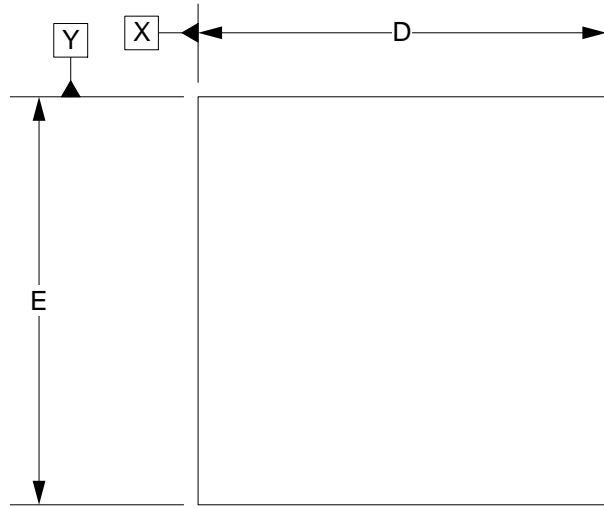
Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout
Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$]
unless stated otherwise.


| | | | | |
|---|--|---------------------------|----------|-------------------|
|  | CG-BGA-4011 Drawing © 2011 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com | Status: Released | Scale: - | Rev: B |
| | | Drawing: E. Smolentseva | | Date: 10/26/11 |
| | | File: CG-BGA-4011 Dwg.mcd | | Modified: 3/31/14 |



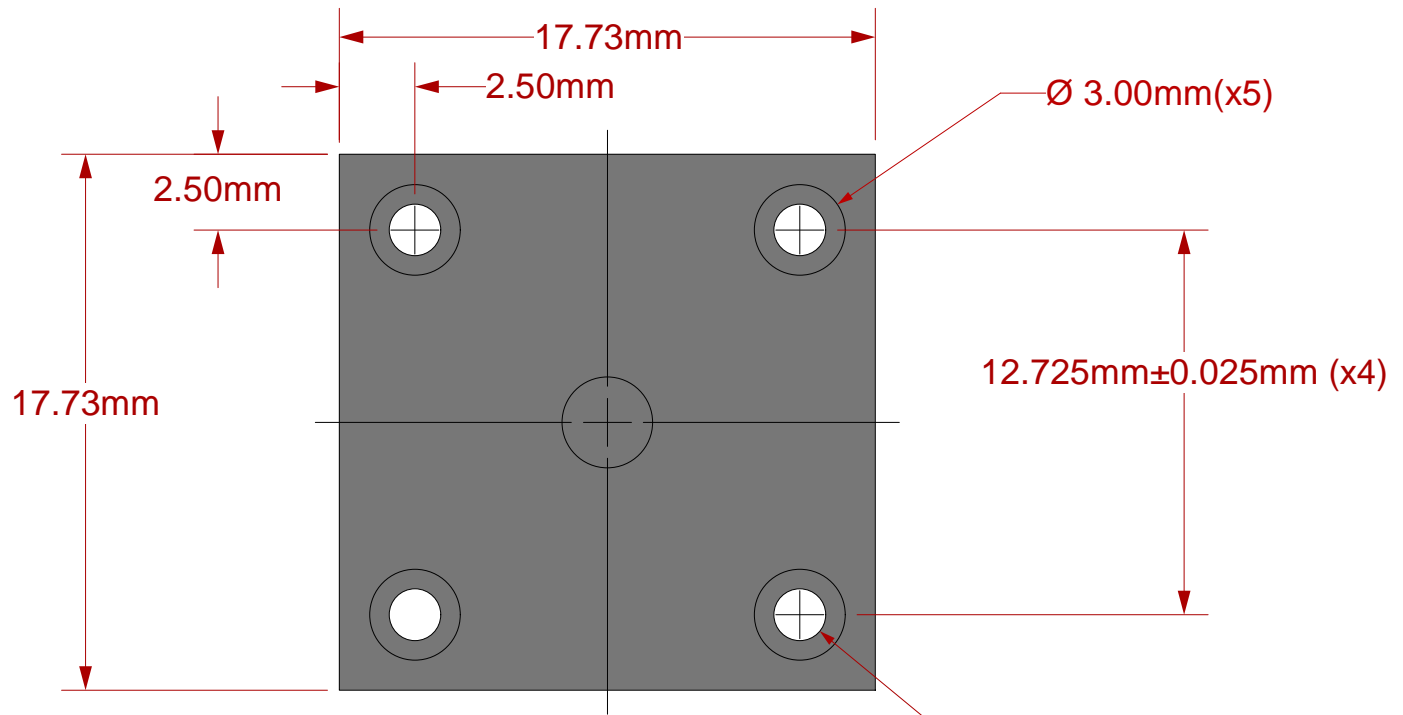
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

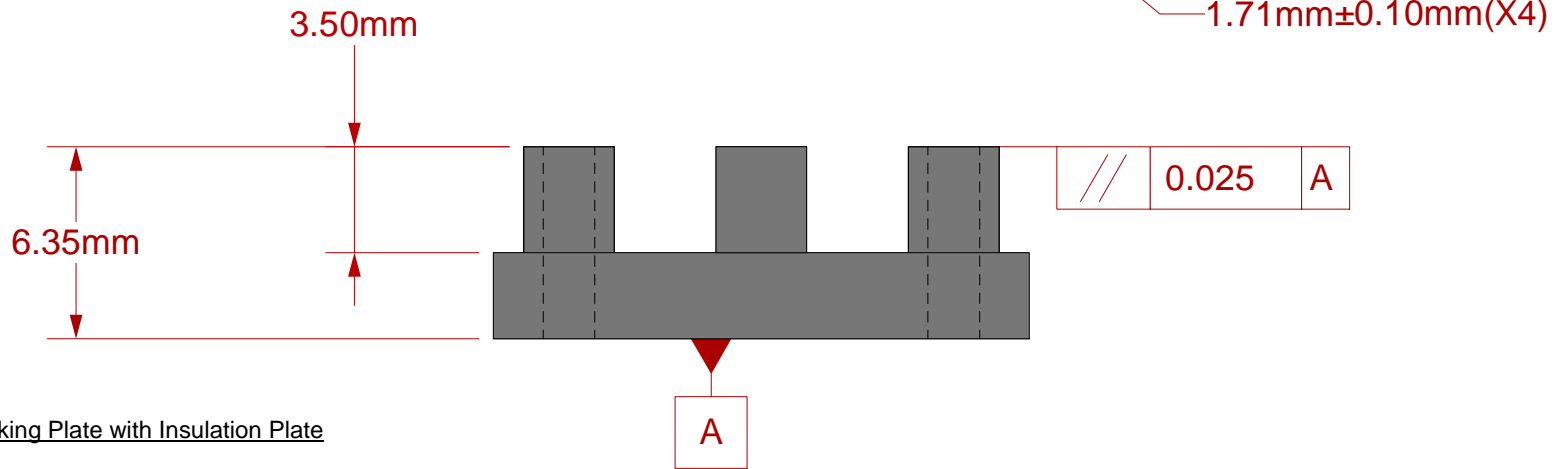
| DIM | MIN | MAX |
|-----|---------|------|
| A | | 1.70 |
| A1 | 0.25 | 0.35 |
| b | | 0.55 |
| D | 9.0 BSC | |
| E | 9.0 BSC | |
| e | 0.8 BSC | |

| | | | | |
|---|--|---------------------------|-------------------|--------|
|  | CG-BGA-4011 Drawing © 2011 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com | Status: Released | Scale: - | Rev: B |
| | | Drawing: E. Smolentseva | Date: 10/26/11 | |
| | | File: CG-BGA-4011 Dwg.mcd | Modified: 3/31/14 | |


Top View



Side View



Description: Backing Plate with Insulation Plate

| | | | | |
|---|--|---------------------------|-------------------|--------|
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| | | Drawing: E. Smolentseva | Date: 10/26/11 | |
| | | File: CG-BGA-4011 Dwg.mcd | Modified: 3/31/14 | |

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)